

WHAT IS CLAIMED IS:

1. A stacked semiconductor chip package comprising:
 - a substrate;
 - a first chip, mounted on the substrate and electrically
5 connected to the substrate by a plurality of electrical leads;
 - a second chip, electrically connected to the substrate by a
plurality of electrical leads and having two opposed longitudinal sides
defining a first length; and
 - a plate, mounted between the first chip and the second chip
10 and connected the first chip and the second chip, corresponding to the two
longitudinal sides of the second chip, the plate having two opposed
longitudinal sides defining a second length, the second length being larger
than the first length to expose the opposed longitudinal sides of the plate.
2. The stacked semiconductor chip package according to Claim 1,
15 wherein corresponding to the two longitudinal sides of the second chip, the
first chip has two opposed longitudinal sides defining a third length, and
the third length is larger than the second length.
3. The stacked semiconductor chip package according to Claim 1
or 2, wherein corresponding to the two longitudinal sides of the second
20 chip, the second chip further has two opposed transverse sides defining a
first width, the plate further has two opposed transverse sides defining a
second width, the second width is smaller than the first width.
4. The stacked semiconductor chip package according to Claim 3,
wherein the first chip further has two opposed transverse sides defining a
25 third width, and the second width is smaller than the third width.